



OIPC Docket No.: P2000,0361

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1480, on the date indicated below.

By: _____

Date: August 15, 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applic. No. : 10/609,464 Confirmation No: 7300
Applicant : Wolfgang Dickenscheid, et al.
Filed : June 27, 2003
Title : Method for Characterizing and Simulating a Chemical
Mechanical Polishing Process
Art Unit : 2125
Examiner : Kidest Bahta

Docket No. : P2000,0361
Customer No. : 24131

INFORMATION DISCLOSURE STATEMENT
UNDER 37 C.F.R. 1.97(i)

Hon. Commissioner for Patents

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following publications are submitted herewith:

1997 Proceedings Second International Chemical-Mechanical Polish (C.M.P.) for ULSI Multilevel Interconnection Conference (CMP-MIC). "A Mechanical Model for Dram Dielectric Chemical-Mechanical Polishing Process." Catalog No. 97ISMIC-200P, Library of Congress No. 89-644090, February 13-14, 1997, Santa Clara, CA, pp. 259-265.

It is believed that the enclosed prior art is less pertinent than the prior art previously submitted and cited by the Examiner. Kindly place the references in the Patent Office file wrapper. UNDER 37 C.F.R. 1.97(i)

Respectfully submitted,

For Applicants

Date: August 15, 2005

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FORM PTO-1449 (SUBSTITUTE)		Attorney Docket No.: P2000,0361	Applic. No. 10/609,464
U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		Applicant Wolfgang Dickenscheid, et al.	
O P E AUG 18 2003 INFORMATION DISCLOSURE STATEMENT BY APPLICANT (37 CFR 1.98(b))		Filing Date June 27, 2003	Group Art Unit 2125
U.S. PATENT DOCUMENTS			

EXAMINER INITIALS		PATENT NO.	DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE
	A						
	B						
	C						
	D						
	E						
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	G						
	H						
	I						

FOREIGN PATENT DOCUMENT

		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB CLASS	TRANSL. YES NO
	J						
	K						
	L						
	M						
	N						

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

	O	1997 Proceedings Second International Chemical-Mechanical Polish (C.M.P.) for ULSI Multilevel Interconnection Conference (CMP-MIC). "A Mechanical Model for Dram Dielectric Chemical-Mechanical Polishing Process." Catalog No. 97ISMIC-200P, Library of Congress No. 89-644090, February 13-14, 1997, Santa Clara, CA, pp. 259-265.
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EXAMINER	DATE CONSIDERED
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	